



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20190821000
Datasheet for TLV702
Information Only**

Date: October 02, 2019
To: PREMIER FARNELL PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV70212DBVT	null
TLV70218DBVR	null
TLV70218DBVT	null
TLV70225DBVR	null
TLV70229DBVT	null
TLV70233DBVR	null
TLV70233DBVT	null
TLV70235DBVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190821000	PCN Date:	Oct. 2, 2019
Title:	Datasheet for TLV702		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TLV702

SLVSAG6D – SEPTEMBER 2010 – REVISED JULY 2019

Changes from Revision C (March 2015) to Revision D

Page

- Changed OUT pin number from 5 to 3 in WSON column of Pin Functions table 3
- Added footnote to maximum EN voltage specification 4
- Added parameter names to *Recommended Operating Conditions* table 4

The datasheet number will be changing.

Device Family	Change From:	Change To:
TLV702	SLVSAG6C	SLVSAG6D

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/TLV702>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TLV70212DBVR	TLV70228DSER	TLV70230DBVT	TLV70236DSER
TLV70212DBVT	TLV70228DSET	TLV70231DBVR	TLV70236DSET
TLV70215DBVR	TLV70228PDBVR	TLV70231DBVT	TLV70237DBVR
TLV70215DBVT	TLV70228PDBVT	TLV70233DBVR	TLV70237DBVT
TLV70218DBVR	TLV70229DBVR	TLV70233DBVT	TLV70237DSER
TLV70218DBVT	TLV70229DBVT	TLV70233DSER	TLV70237DSET
TLV70225DBVR	TLV70229DSER	TLV70233DSET	TLV70245DBVR
TLV70225DBVT	TLV70229DSET	TLV70235DBVR	TLV70245DBVT
TLV70225DSER	TLV70230DBVR	TLV70235DBVT	TLV702475DBVR
TLV70225DSET	TLV702475DBVT		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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